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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: FUJISAWA, et al.  
Serial No.: 10/611,910  
Filed: July 3, 2003  
For: METHOD OF MANUFACTURING SEMICONDUCTOR  
PACKAGE INCLUDING FORMING A RESIN SEALING  
MEMBER (AS AMENDED)  
Group: 2814  
Examiner: P. Cao

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 9, 2004

Sir:

In response to the Office Action mailed April 8, 2004, please amend the above-identified application as listed in the following, and as set forth on the following pages:

**Amendments to the Specification**

**Amendments to the Claims**

**Remarks** are included following the amendments